

1909782-1 ✓ ACTIVE

AMP SLIM

TE Internal #: 1909782-1

PCB Mount Header, Right Angle, Wire-to-Board, 2 Position, 1.2 mm [.047 in] Centerline, Partially Shrouded, Gold Flash, Surface Mount, Signal, AMP SLIM

[View on TE.com >](#)



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Wire-to-Board**

Number of Positions: **2**

Centerline (Pitch): **1.2 mm [.047 in]**

Features

Product Type Features

PCB Connector Type	PCB Mount Header
Connector System	Wire-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Right Angle
Number of Positions	2
Number of Rows	1

Electrical Characteristics

Operating Voltage	50 VDC
-------------------	--------

Body Features



Primary Product Color	Black
-----------------------	-------

Contact Features

PCB Contact Termination Area Plating Material Finish	Matte
------------------------------------------------------	-------

PCB Contact Termination Area Plating Material Thickness	2.54 μm [100 μin]
---------------------------------------------------------	------------------------------------------

Contact Layout	Inline
----------------	--------

Contact Base Material	Phosphor Bronze
-----------------------	-----------------

PCB Contact Termination Area Plating Material	Tin
-----------------------------------------------	-----

Contact Mating Area Plating Material	Gold Flash
--------------------------------------	------------

Contact Mating Area Plating Material Thickness	1.27 μm [50 μin]
------------------------------------------------	-----------------------------------------

Contact Type	Pin
--------------	-----

Contact Current Rating (Max)	2 A
------------------------------	-----

Termination Features

Termination Method to PCB	Surface Mount
---------------------------	---------------

Mechanical Attachment

PCB Mount Retention Type	Solder Peg
--------------------------	------------

Mating Alignment Type	Polarization
-----------------------	--------------

PCB Mount Alignment	Without
---------------------	---------

Mating Retention	With
------------------	------

PCB Mount Retention	With
---------------------	------

Connector Mounting Type	Board Mount
-------------------------	-------------

Mating Alignment	With
------------------	------

Housing Features

Centerline (Pitch)	1.2 mm[.047 in]
--------------------	-----------------

Housing Material	Liquid Crystal Polymer (LCP) GF30
------------------	-----------------------------------

Dimensions

Connector Width	4.3 mm[.169 in]
-----------------	-----------------

Connector Height	1.4 mm[.055 in]
------------------	-----------------

Connector Length	4.2 mm[.165 in]
------------------	-----------------

Usage Conditions

Operating Temperature Range	-25 – 85 $^{\circ}\text{C}$ [-13 – 185 $^{\circ}\text{F}$]
-----------------------------	-------------------------------------------------------------

Operation/Application

Circuit Application	Signal
---------------------	--------



Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

Packaging Features

Packaging Quantity	4000
Packaging Method	Reel

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2025 (250) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

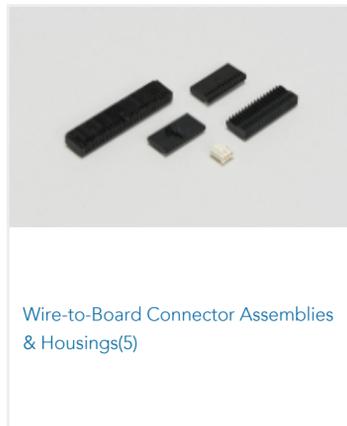
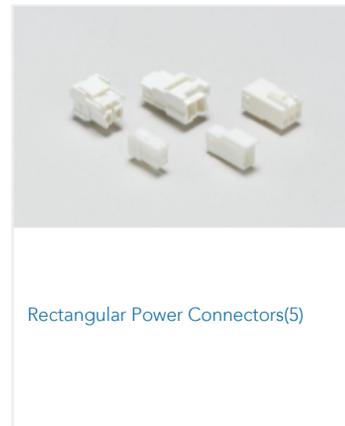
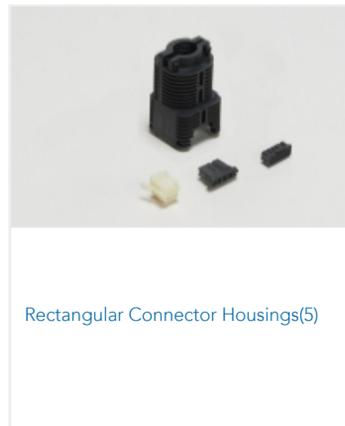
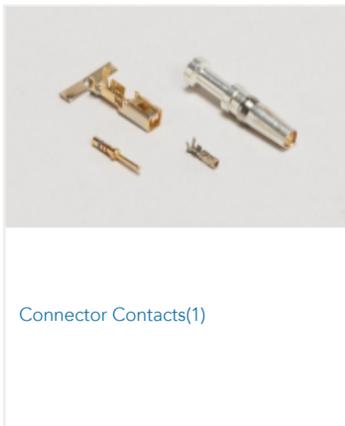
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | AMP SLIM



Customers Also Bought





Documents

Product Drawings

[BOARD TO WIRE WAFER 1.2MM TOP ENTRY](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_1909782-1_A4.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1909782-1_A4.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1909782-1_A4.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Application Specification](#)

English